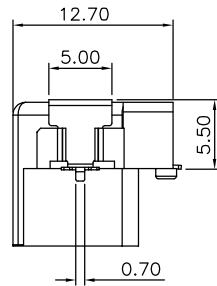
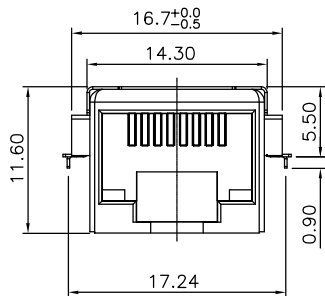
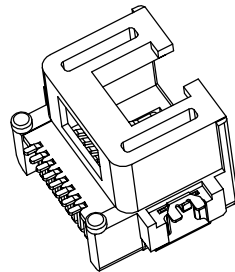
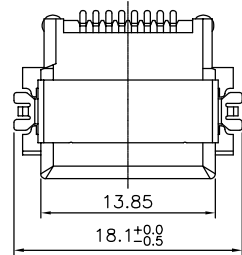


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements



8	—
7	—
6	RX-
5	—
4	—
3	RX+
2	TX-
1	TX+
PIN序	说明

NOTE:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING: LCP UL94V-0
- 1-2.SHELL: 0.20mm THICKNESS COPPER ALLOY
- 1-3.CONTACT: PHOSPHOR BRONZE T=0.30MM

2.PLATING SPECIFICATION:

- G/F PLATING OVER NI
- 100u"SN PLATED ON SOLDER TALL AREA
- 50u"NI UNDER PLATED OVER ALL
- 2-1.SHELL: Ni 30U" MIN PLATING OVER ALL

3.MECHANICAL PERFORMANCE:

- 3-1.INSERTION FORCE: 22N MAX
- 3-2.REMOVAL FORCE: 22N MAX
- 3-2.DURABILITY: 750 CYCLES MIN.

4.ELECTRICAL PERFORMANCE:

- 4-1.CURRENT RATING:1.5A
- 4-2.VOLTAGE RATING:125V MAX
- 4-3.CONTACT RESISTANCE: 40mΩ Max.
- 4-4.INSULATION RESISTANCE: 500MΩ MIN
- 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC Min

5.ENVIRONMENTAL PERFORMANCE:

- OPERATING TEMPERATURE: -40°C~+85°C.

6.PACKAGE SPEC:TRAY

P/N:

WLR4F9-08 8 X X X 023

PLATING:

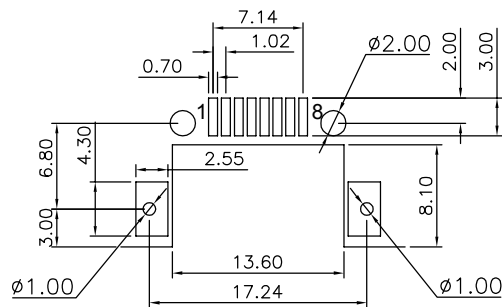
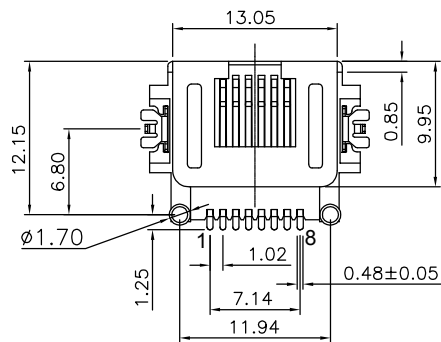
- 1-G/F
- 2-Au 3u"
- 3-Au 6u"
- 5-Au 15u"
- 6-Au 30u"

HOUSING:

- 1-PBT
- 2-LCP
- 3-PA9T

COLOUR:

A-BLACK



PCBLAYOUT TOP VIEW  
TOL ±0.05

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	21.01.13	WLR4F9-088XXX023	ENDE05	
			UNIT:mm	0.00±0.25	X°±3°	DESIGNER	Han_Gao	21.01.13	TITLE:		REV: A0      SHEET: 1/1
			SIZE: A4	0.000±0.10	X°X' ±2°	DRAWN	Zijun_Huang	21.01.13	RJ45 8P8C SMT沉板式5.5MM		